

HSF

NOTES:

Current Rating: 1.0AMP
Contact Resistance: 20mΩ Max
Withstand Voltage: 500V AC/DC
Insulation Resistance: 1000MΩ Min
Operation Temperature: -40°C to +105°C

Contact Material: Phosphor Bronze
Contact plating: Au Or Sn over Ni
Insulator Material: PA9T+30%G.F UL94V-0

Ordering Information

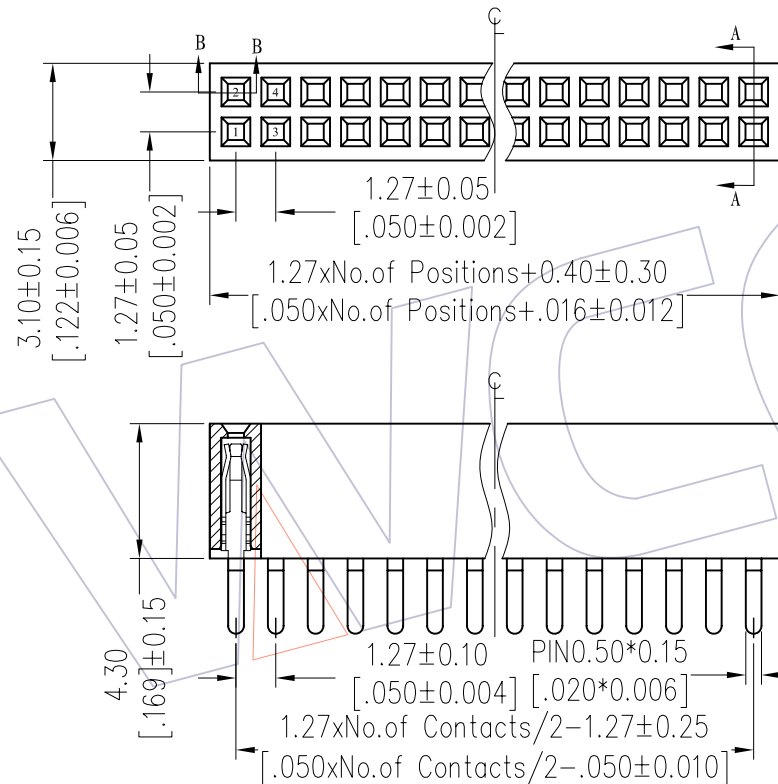
2344-2 XX S XX CUN T 1

No. of Pins per
Row: 02~50Pin

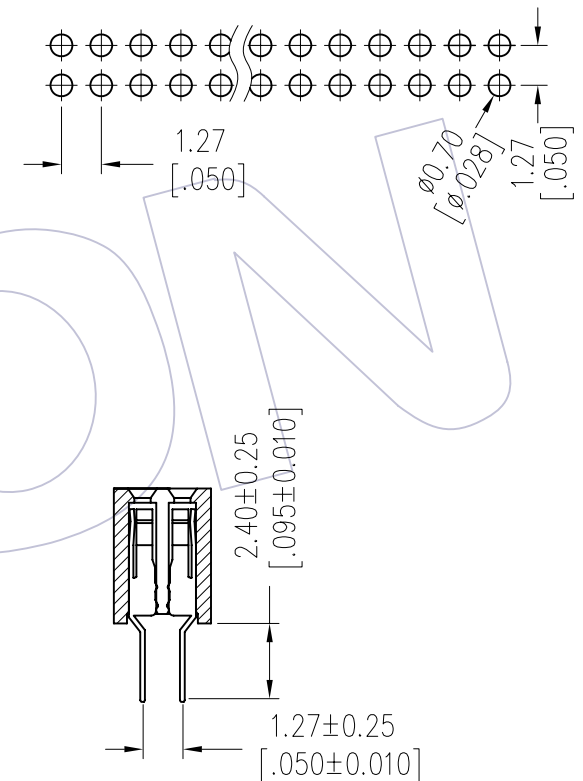
Contact Plating:
G0=Gold Flash
G3=10μ"Gold
G4=15μ"Gold
G5=30μ"Gold
S0=Gold Flash/Tin
S3=10μ"Gold/Tin
S4=15μ"Gold/Tin
S5=30μ"Gold/Tin
SN=Tin

Packing:
T=Tube
P=Tube+CAP
R=Tape&Reel+CAP

Recommended P.C.B Layout(Top Side)
(PCB BOARD TOLERANCE±0.05)



SECTION B-B



SECTION A-A

Item	Pitch	Mating
Standard	1.27	1310/1315/1320/3131/3133/3100
Alternate		

REV	DATE	MODIFICATION DESCRIPTION	CHANGE	OPERATION	DRAW	DATE	SCALE	FIT	PART NO.		
				X.X ±0.40	JYHuang	2012/07/09	UNIT	mm	2344-2XXSXXCUNT1		
				X.XX ±0.25	CHECK	DATE	SIZE	A4	TITLE:		
				X.XXX ±0.15			SHEET	1/1	FH1.27mm DUAL ROW 180° DIP		
				Angle ± 3°	APPROVE	DATE	PROJ.	1/1	H=4.30		
				DIM TOL					Customer NO.		